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APR -3 2002 Atty. Docket

TECHNOLOGY CENTER 2880 018154

In re Application of

MIKE C. LOO

Serial No. 10/001,271

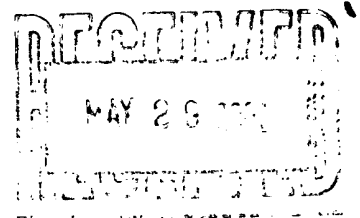
Filed: Nov. 20, 2001

Group Art Unit: 2835

Title: Optimum Power and Ground Bump Pad and Bump Patterns
For Flip Chip Packaging

Commissioner for Patents
Washington, D.C. 20231

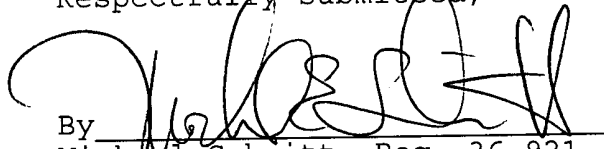
LETTER TO OFFICIAL DRAFTSMAN



Sir:

Enclosed are formal drawings for filing in the
above-identified application.

Respectfully submitted,

By 
Michael Schmitt, Reg. 36,921
Attorney
(408) 617-4745

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited this date with the United States Postal Service as
first-class mail in an envelope addressed to:

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On Mar. 21, 2002
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By Carol Bryant
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